

MURH840CTG

Power Rectifier

Features and Benefits

- Low Forward Voltage
- Low Power Loss/High Efficiency
- High Surge Capacity
- 175°C Operating Junction Temperature
- 8 A Total (4 A Per Diode Leg)
- These are Pb-Free Devices*

Applications

- Power Supply – Output Rectification
- Power Management
- Instrumentation

Mechanical Characteristics

- Case: Epoxy, Molded
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Rating: Human Body Model 3B
Machine Model C

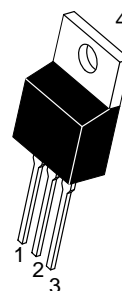
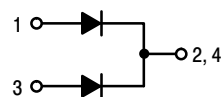


ON Semiconductor®

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ULTRAFAST RECTIFIER
8.0 AMPERES, 400 VOLTS

$t_{rr} = 28 \text{ ns}$



TO-220AB
CASE 221A

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
UH840 = Device Code
G = Pb-Free Package
AKA = Diode Polarity

ORDERING INFORMATION

Device	Package	Shipping
MURH840CTG	TO-220 (Pb-Free)	50 Units/Rail

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MURH840CTG

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	400	V
Average Rectified Forward Current ($T_C = 155^\circ\text{C}$) Per Leg Total Device	$I_{F(AV)}$	4.0 8.0	A
Peak Repetitive Forward Current per Diode Leg (Square Wave, 20 kHz, $T_C = 149^\circ\text{C}$)	I_{FM}	8.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I_{FSM}	100	A
Controlled Avalanche Energy	W_{AVAIL}	20	mJ
Operating Junction and Storage Temperature Range	T_J, T_{stg}	-65 to +175	$^\circ\text{C}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

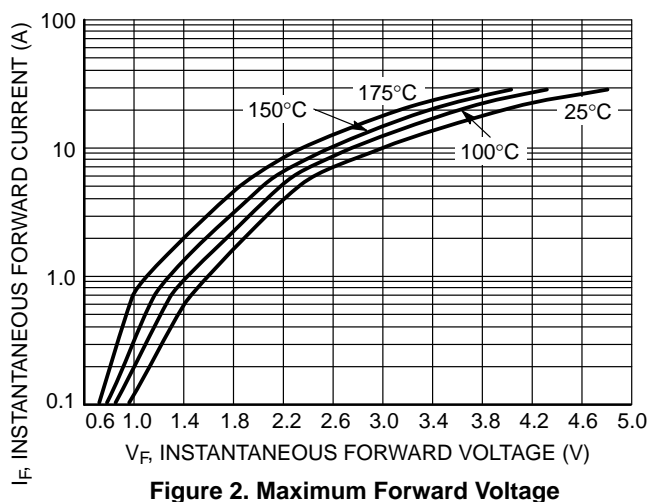
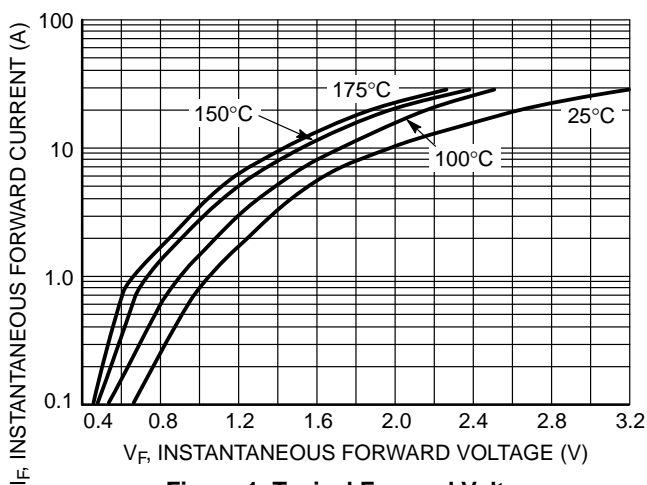
THERMAL CHARACTERISTICS

Characteristic	Conditions	Symbol	Max	Unit
Maximum Thermal Resistance, Junction-to-Case	Min. Pad	$R_{\theta JC}$	3.0	$^\circ\text{C/W}$
Maximum Thermal Resistance, Junction-to-Ambient	Min. Pad	$R_{\theta JA}$	60	

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Min	Typical	Max	Unit
Maximum Instantaneous Forward Voltage (Note 1) ($i_F = 4.0\text{ A}$, $T_J = 150^\circ\text{C}$) ($i_F = 4.0\text{ A}$, $T_J = 25^\circ\text{C}$)	V_F	-	1.12 1.45	1.9 2.2	V
Maximum Instantaneous Reverse Current (Note 1) (Rated dc Voltage, $T_J = 150^\circ\text{C}$) (Rated dc Voltage, $T_J = 25^\circ\text{C}$)	i_R	-	300 4.0	500 10	μA
Maximum Reverse Recovery Time ($I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$)	t_{rr}	-	-	28	ns

1. Pulse Test: Pulse Width = 300 μs , Duty Cycle $\leq 2.0\%$.



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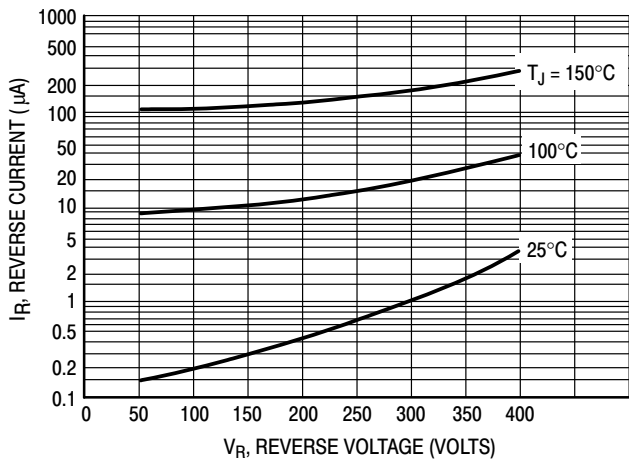


Figure 3. Typical Reverse Current, Per Leg

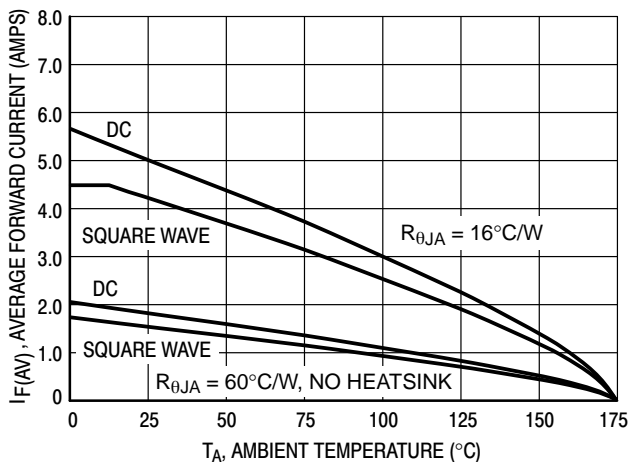


Figure 4. Forward Current Derating, Ambient, Per Leg

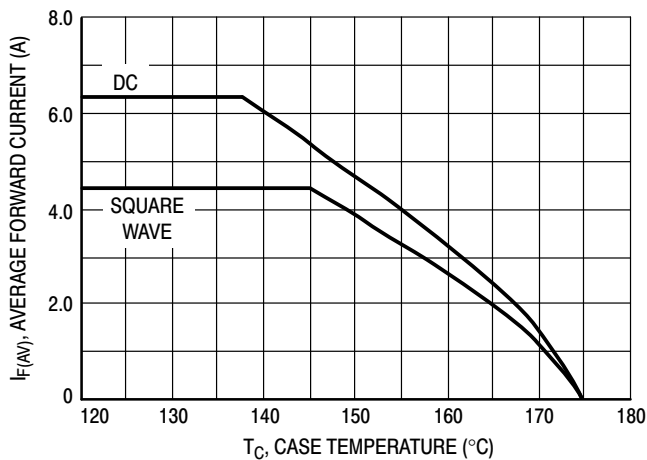


Figure 5. Current Derating, Case, Per Leg

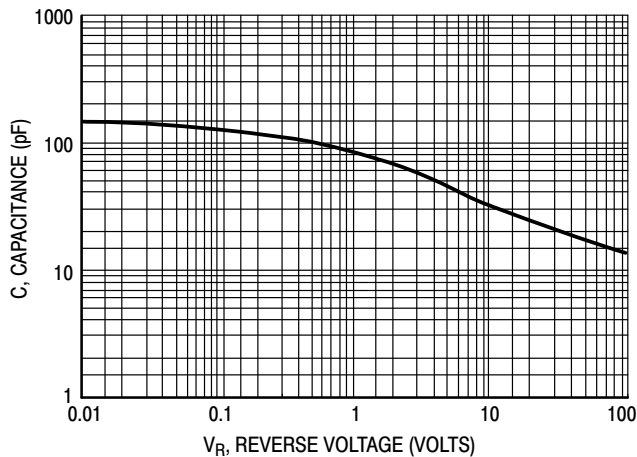


Figure 6. Typical Capacitance, Per Leg

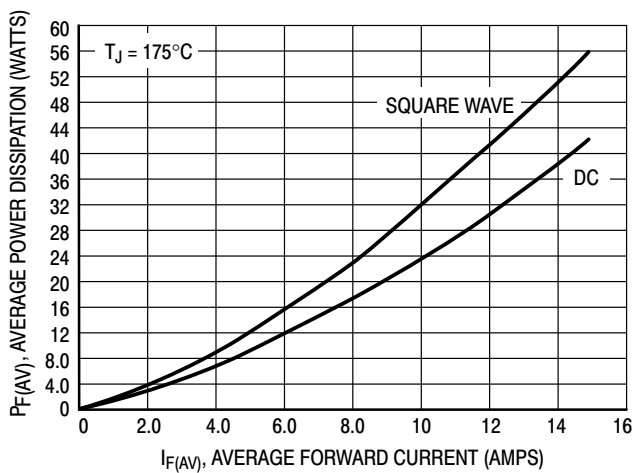
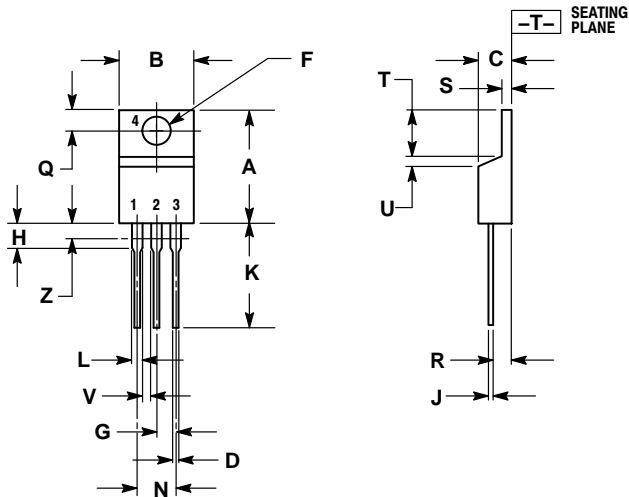


Figure 7. Power Dissipation, Per Leg

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PACKAGE DIMENSIONS

TO-220
CASE 221A-09
ISSUE AH




NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.570	0.620	14.48	15.75
B	0.380	0.415	9.66	10.53
C	0.160	0.190	4.07	4.83
D	0.025	0.038	0.64	0.96
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
H	0.110	0.161	2.80	4.10
J	0.014	0.024	0.36	0.61
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
T	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
V	0.045	---	1.15	---
Z	---	0.080	---	2.04

STYLE 6:

- PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE

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